

■ Features

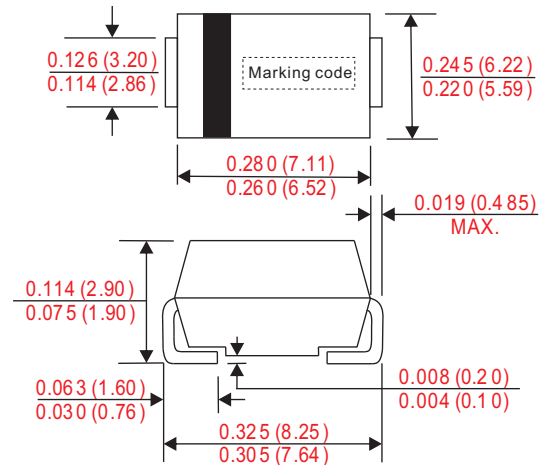
- Low profile surface mounted application in order to optimize board space.
- High current capability, low forward voltage drop.
- High surge capability.
- Superfast recovery time for switching mode application.
- Glass passivated chip junction.
- Suffix "G" indicates Halogen-free part, ex. ES5ACG.
- Lead-free parts meet environmental standards of MIL-STD-19500 /228

■ Mechanical data

- Epoxy: UL94-V0 rated flame retardant
- Case : Molded plastic, DO-214AB / SMC
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Weight : 0.007 ounce, 0.226 gram

■ Outline

SMC(DO-214AB)



Dimensions in inches and (millimeters)

■ Maximum ratings and electrical characteristics

Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Parameter	Conditions	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current		I_o			5.0	A
Forward surge current	8.3ms single half sine-wave superimposed on rate load (JEDEC method)	I_{FSM}			125	A
Reverse current	$V_R = V_{RRM}$ $T_A = 25^\circ\text{C}$	I_R			5.0	uA
	$V_R = V_{RRM}$ $T_A = 125^\circ\text{C}$				300	
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	C_j		45		pF
Storage temperature		T_{STG}	-55		+150	°C

Symbol	Marking code	Max. repetitive peak reverse voltage V_{RRM} (V)	Max. RMS voltage V_{RMS} (V)	Max. DC blocking voltage V_R (V)	Max. forward voltage @5A, $T_A = 25^\circ\text{C}$ V_F (V)	Max. reverse recovery time(1) T_{rr} (ns)	Operating temperature T_J (°C)
ES5AC	ES5A	50	35	50	0.95	35	-55 ~ +150
ES5BC	ES5B	100	70	100			
ES5DC	ES5D	200	140	200			
ES5GC	ES5G	400	280	400	1.25		
ES5JC	ES5J	600	420	600	1.70		

Note : 1. $I_F = 0.5A$, $I_R = 1.0A$, $I_{RR} = 0.25A$

Rating and characteristic curves

FIG.1- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTIC

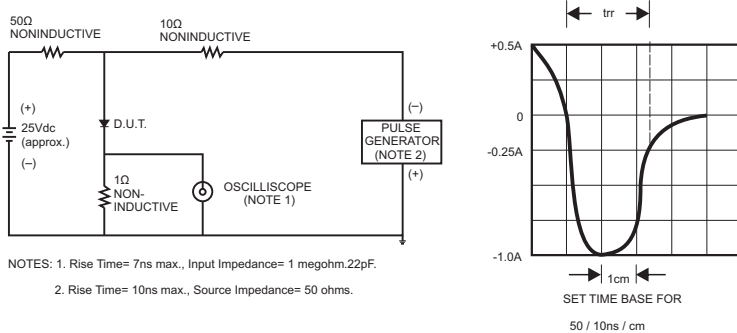


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

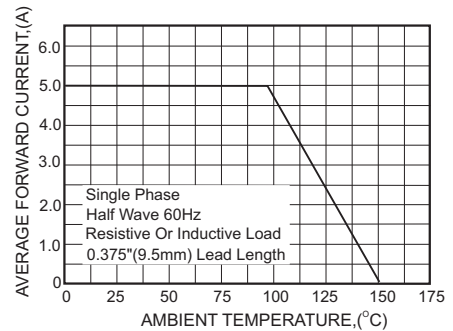


FIG. 3 - TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

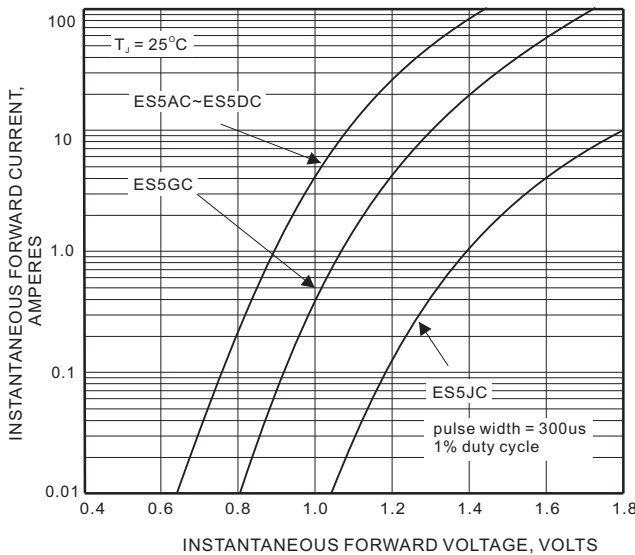


FIG.4-TYPICAL REVERSE CHARACTERISTICS

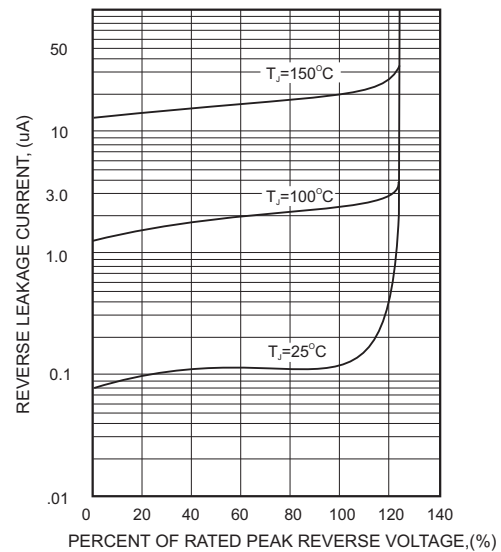


FIG.5-MAXIMUM NON-REPETITIVE

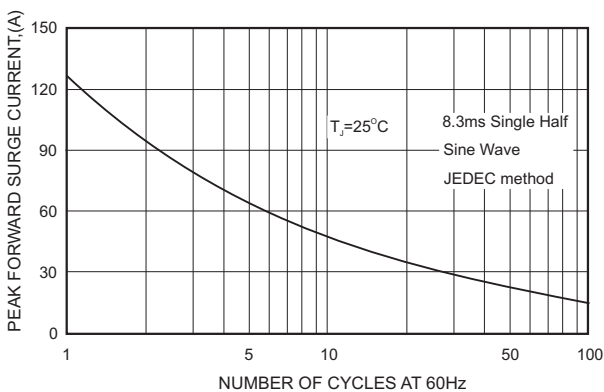
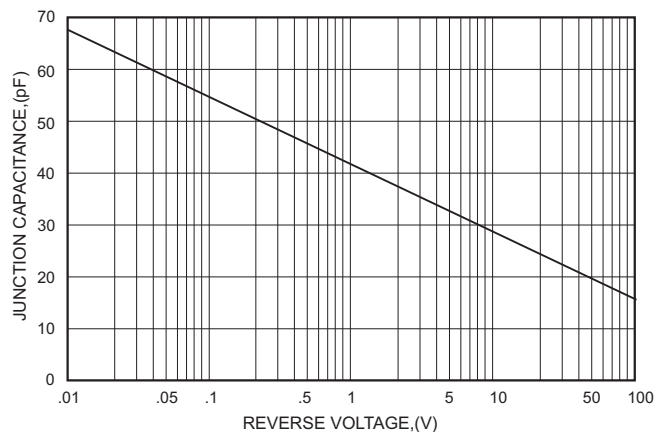


FIG.6-TYPICAL JUNCTION CAPACITANCE



■ SMC foot print



A	B	C
0.132 (3.30)	0.098 (2.50)	0.176 (4.40)

Dimensions in inches and (millimeters)

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